

Specification

Client Name : _____

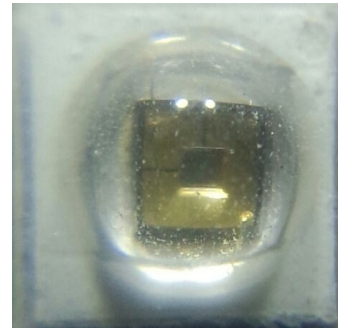
Client P/N : OF-SMD3535UV-B

Product P/N : _____

Sending Date: _____



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES



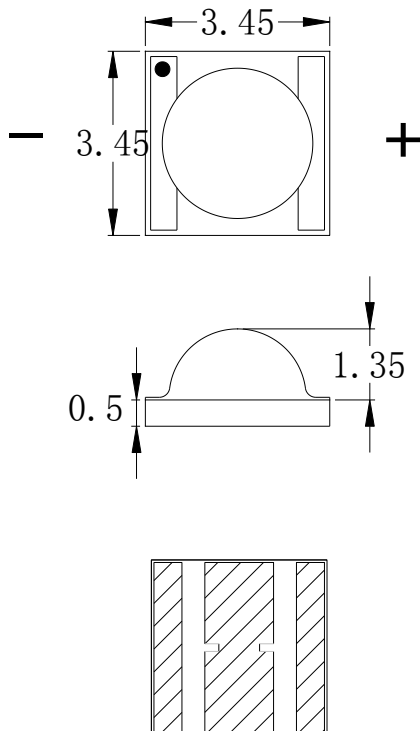
Features

Dimension 3.45mm×3.45mm×1.5mm
Viewing angle 120°
RoHS compliant
Anti-vulcanization
Reflow Solder-able

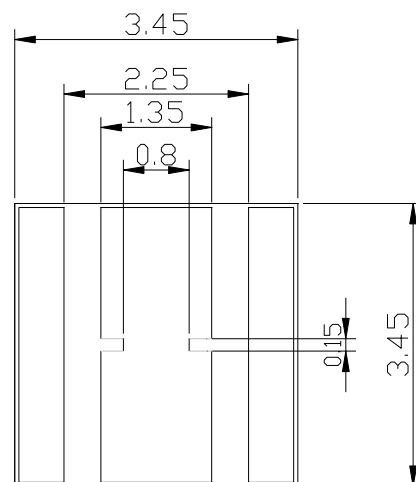
Applications

Fluorescent spectroscopy
Sensors and monitors
Bio-analysis/detection
Phototherapy
Disinfection

Package Dimensions



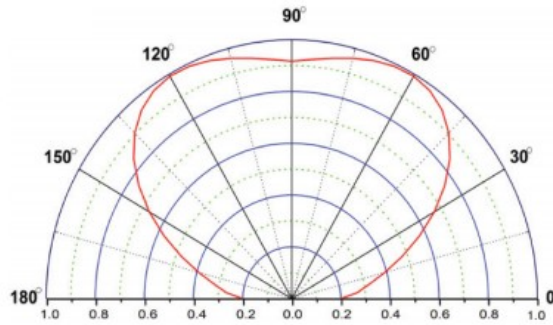
Recommended Soldering



Notes

1. All dimension units are millimeters.
2. All dimension tolerance is $\pm 0.2\text{mm}$ unless otherwise noted.

Radiation Pattern



Typical Optical/ Electrical Characteristics @T_a=25°C

Parameters 参数	Symbol 符号	Forward Current IF	Min.	Typ.	Max.	Unit
Forward Voltage 正向电压	VF	@20mA	4	5.5	7	V
Optical Power 光功率	P _{out}	@20mA	0.5	1.0	1.5	mW
Peak Wavelength 峰值波长	λ _p	@20mA	305	310	315	—
FWHM 半峰宽	—	@20mA	8	10	—	nm
Lifetime 寿命	L(50)	@20mA	650	700	800	Hour

Notes:

1. Tolerance of measurement of forward voltage±0.1V、peak Wavelength±2.0nm、luminous power±5%

Absolute Maximum Ratings

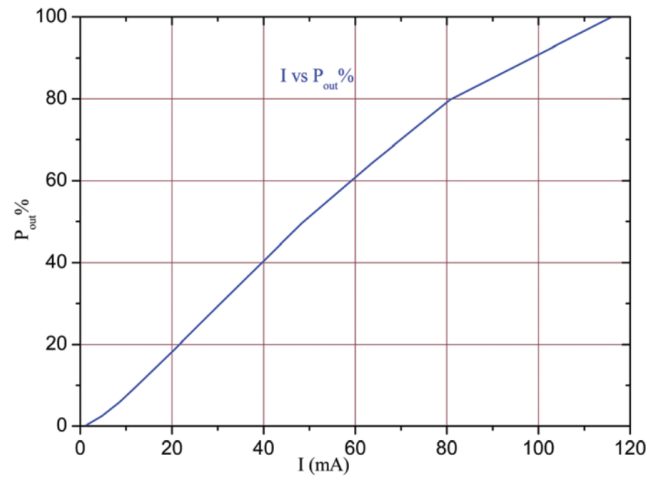
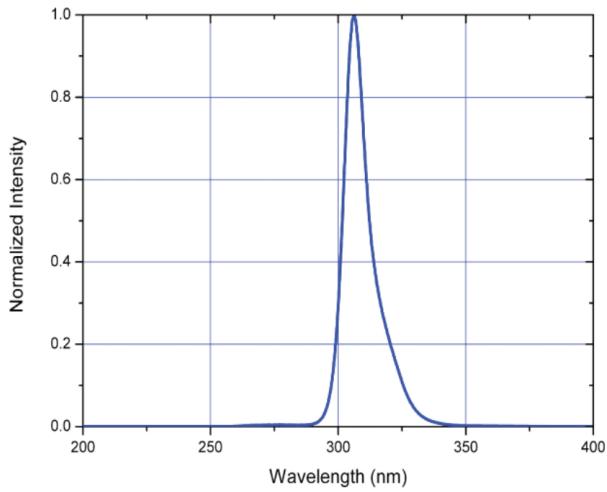
TA=25°C

Parameter参数	Symbol	Rating Value	Units
Input power 输入功率	Pi	0.12	W
Maximum operating current 最大工作电流	IF _{max}	20	mA
Junction Temperature结温	T _j	115	°C
Operating Temperature Range工作温度	Top	-20°C To +45°C	
Storage Temperature Range储藏温度	Tstg	-40°C To +80°C	
Lead Soldering Temperature*引线焊接温度	T _{sol}	Max. 350°C for 5sec Max.	

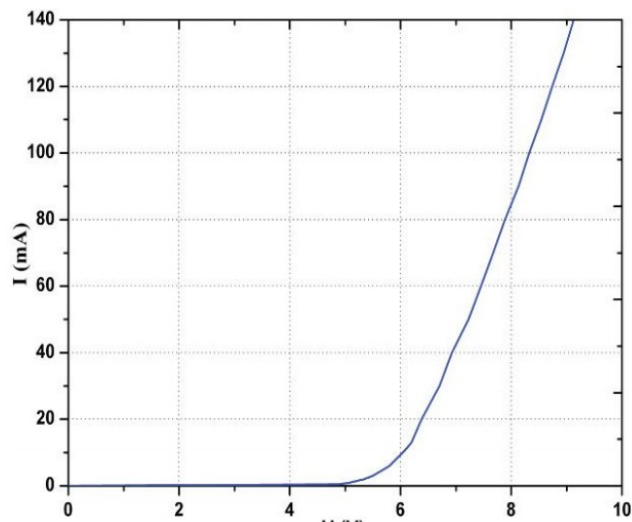
Note:

1. The temperature of Aluminum PCB do not exceed 45°C

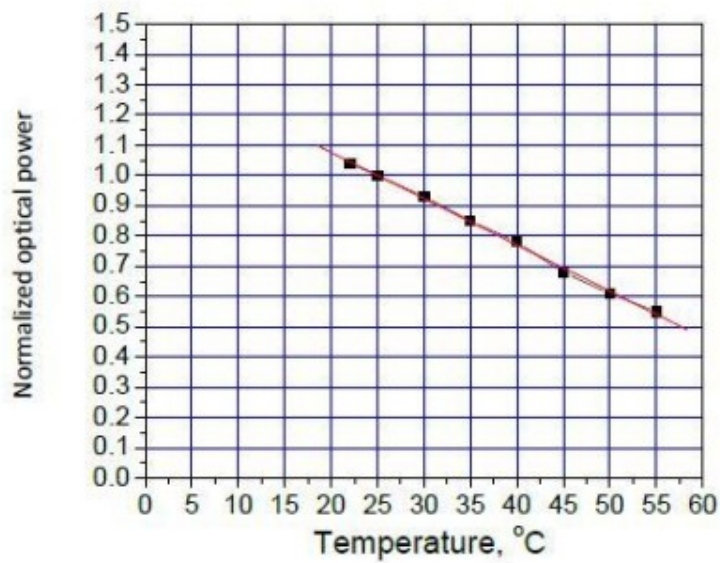
Typical Optical/Electrical Characteristics Curves ($T_a=25^\circ\text{C}$ Unless Otherwise Noted)



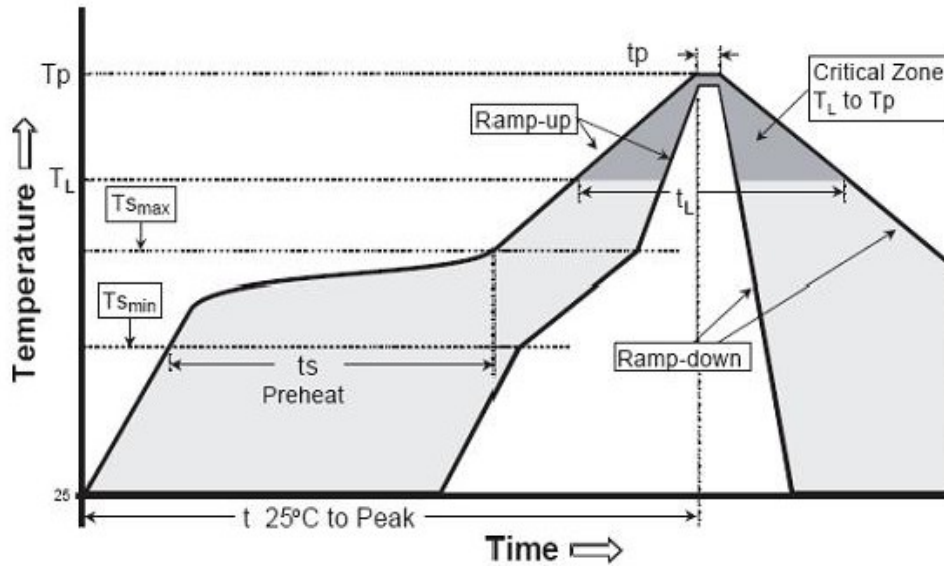
Po vs IF



U-I



Soldering



Reflow soldering

Caution

1. wave peak and soak-stannum soldering etc. is not suitable for this products.
2. reflow soldering should not be done more than one time
3. The peak reflow temperature is $180 \pm 10^\circ\text{C}$, not more than 40 seconds
4. Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, suitable tools have to be used.
5. when soldering, do not put stress on the LEDs during heating.
6. After soldering, do not warp the LED. do not stack PCBS or assemblies containing K Series LEDs so that anything rests on the LED lens.

Test

1. All Deep UV LED products mounted on aluminum metal-core printed circuit board, can be lighted directly, but we do not recommend lighting the Deep UV LED products for more than 5 seconds without an appropriate heat dissipation equipment.

Label

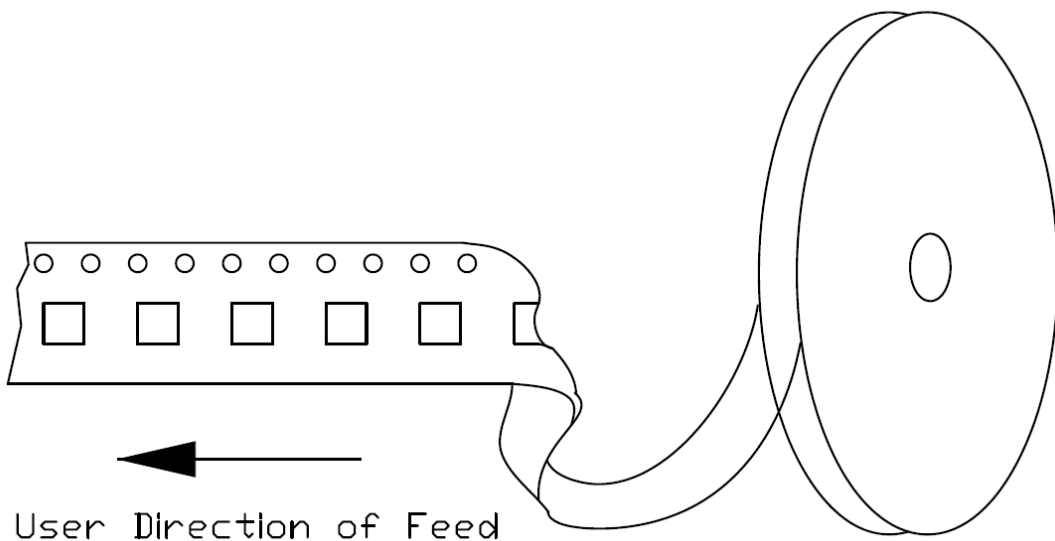
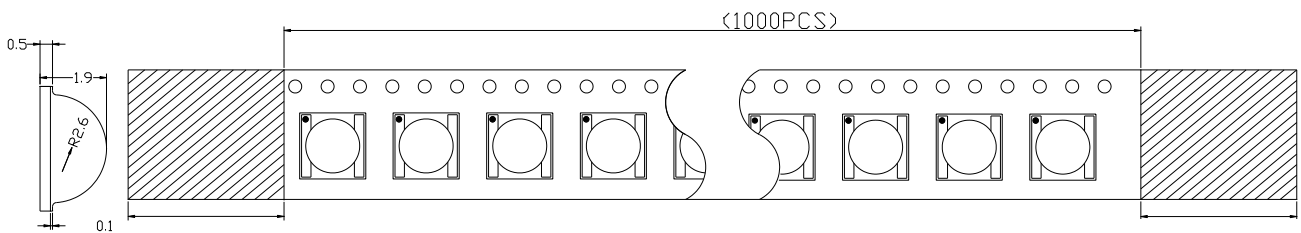
		RoHS
TYPE:		QTY:
VF:	IF:	λ_p :
P_{out} :		
DATE:	LOT.NO:	

P_{out} : Optical Power

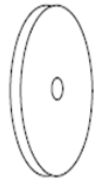
VF: Forward voltage rank

λ_p : Peak Wavelength

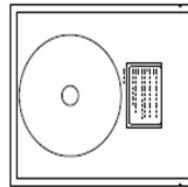
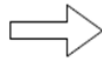
Tape Specifications(Units:mm)



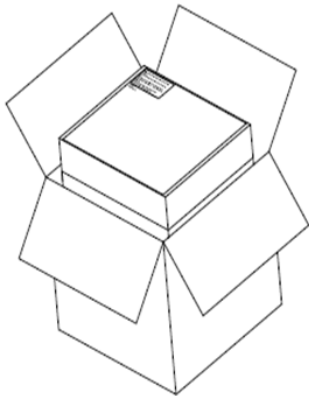
Packing



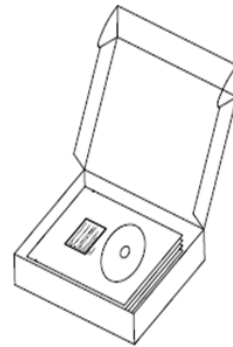
Reel: 1000pcs



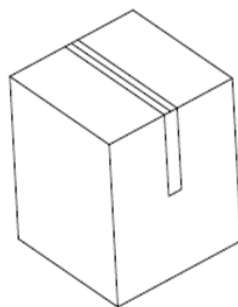
1Reel/ESD Shilding Bag



5Inner Box/Outer Box : 25000pcs



5Bags/Inner Box : 5000pcs



Outer Box : 25000pcs

Precaution for use

1.Storage

To avoid the moisture penetration ,we recommend storing LEDs in a dry box (or a desiccator) with a desiccant. The recommended conditions are temperature 5 to 30 degrees Centigrade. Humidity 60% maximum.

2.Precaution after opening packing:

2.1.Soldering should be done right after opening the package (within 24Hrs).

2.2.Keeping of a fraction.

-Sealing:

-Temperature: 5~30°C ; Humidity: less than 30%

2.3.If the package has been opened than 1 week or the color of desiccant changed, components should be dried for 10-12 Hrs at 60±5°C.

3.Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temperature after soldering.

4.Please avoid rapid cooling after soldering.

5.Components should not be mounted on warped direction of PCB.

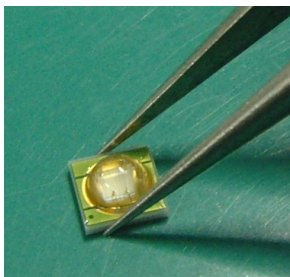
6.This device should not be used in any fluid such as water, oil ,organic solvent etc. When washing is required, Isopropyl Alcohol should be used.

7.Avoid touching Resin parts especially by sharp tools such as pincette

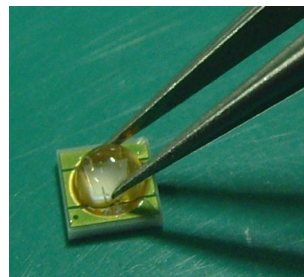
8.Please do not force over 1000g impact or pressure diagonally on the silicone resin. It will cause fatal damage on this product.

9.Please do not cover the silicone resin of the LEDs with other resin.

10.Do not use metal suction nozzle, rubber or silica gel suction nozzle is recommended.



OK



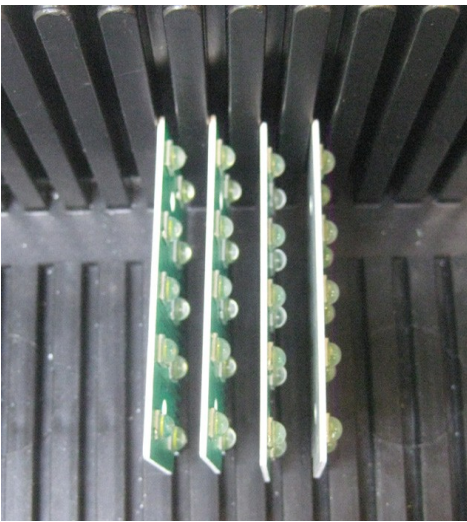
NG

Note

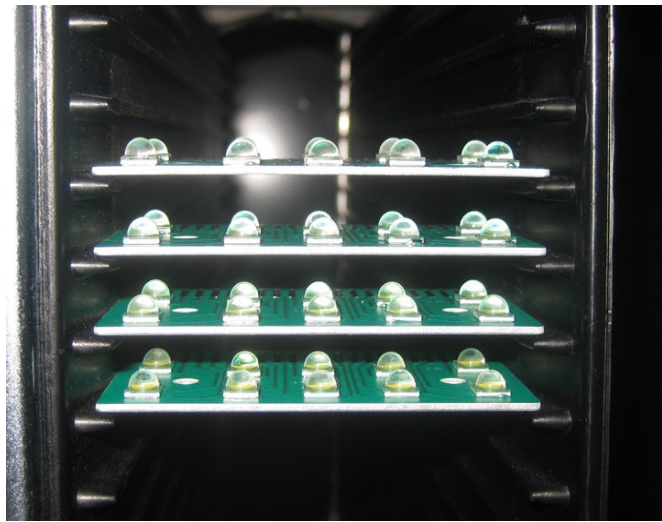
1. $\theta_{1/2}$ is the angle from optical centerline where the luminous power is 1/2 the optical centerline value.

2.The value only for reference.

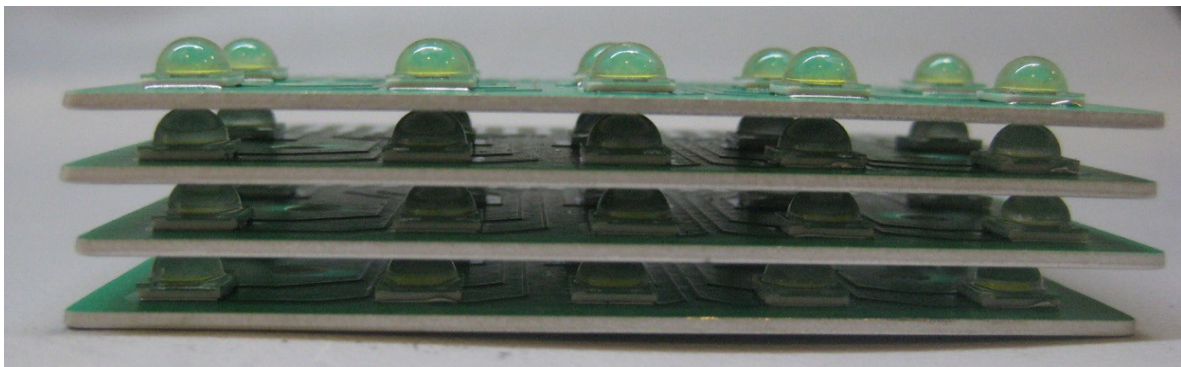
13. Do not stack PCBs or assemblies containing the LEDs so that anything rests on the LED resin. Force applied to the LED resin may result in the resin being knocked off. PCBs or assemblies containing the LEDs should be stacked in a way to allow at least 2 cm clearance above the LED resin.



OK



OK



NG